

The first Manhattan direction includes either a horizontal or vertical direction, and the second Manhattan direction includes either a horizontal or vertical direction, opposite from the first Manhattan direction. In one embodiment, the Manhattan directional wires are configured to simulate a 45 degree wiring direction, and, in another embodiment, the Manhattan directional wires are configured to simulate a 60 degree wiring direction. The pairs of conductors may be configured, essentially in parallel, to generate tracks of conductor on a metal layer in the simulated direction.

IN THE CLAIMS

Please cancel claims 1-35.

REMARKS

This Preliminary Amendments is concurrently filed with the above-entitled application, which is a continuation application of a presently pending application Ser. No. 09/681,776, entitled "Diagonal Wiring Architecture For Integrated Circuit", filed on June 3, 2001, which is a continuation application of a presently pending application Ser. No. 09/733,104, entitled "Multi-Directional Wiring On A Single Metal Layer " filed on December 7, 2000. In this Preliminary Amendment, Applicants have changed the title of this application, inserted a reference to the related parent application, deleted paragraphs in the Summary of the Invention, and canceled claims 1-35. Accordingly, claims 36-47 are currently pending in this application.